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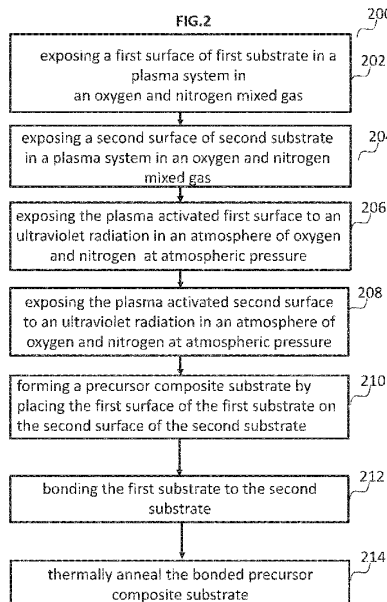
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(54) Title: METHOD OF FORMING A COMPOSITE SUBSTRATE



(57) Abstract: A method of forming a composite substrate is provided. The method includes a mixed gas plasma activation process using oxygen and nitrogen including exposing a surface of a wafer and a surface of a piezoelectric material wafer in a plasma system; exposing the plasma activated surface of the wafer and the plasma activated surface of the piezoelectric material wafer to an ultraviolet radiation in an atmosphere of oxygen and nitrogen; placing the surface of the wafer on the surface of the piezoelectric material wafer; applying a mechanical load on the wafer and the piezoelectric material wafer; and thermally annealing the bonded wafer and piezoelectric material wafer; wherein the wafer is configured to support the piezoelectric material wafer.

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